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### RECORDATION FORM COVER SHEET PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

<p><b>1. Name of conveying party(ies)/Execution Date(s):</b> TESSERA, INC.</p> <p>Execution Date(s): <u>March 25, 2011</u></p> <p>Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>	<p><b>2. Name and address of receiving party(ies)</b></p> <p style="text-align: center;">TESSERA TECHNOLOGIES IRELAND LIMITED</p> <p>Name: _____ Internal Address: _____ Street Address: _____</p> <p>CLIONA BUILDING ONE PARKMORE EAST BUSINESS PARK BALLYBRIT, GALWAY</p> <p>City: _____ State: _____ Country: <u>IRELAND</u> Zip: _____</p> <p>Additional name(s) &amp; address(es) attached: <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>
<p><b>3. Nature of Conveyance:</b></p> <p><input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger  <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name  <input type="checkbox"/> Government Interest Assignment  <input type="checkbox"/> Executive Order 9424, Confirmatory License  <input type="checkbox"/> Other _____</p>	

<p><b>4. Application or patent number(s):</b></p> <p>A. Patent Application No.(s) 12/072,508 12/784,841 12/221,204 11/650,356</p> <p>Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>	<p><input type="checkbox"/> This document is being filed together with a new application.</p> <p>B. Patent No.(s)</p> <p><input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>
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<p><b>5. Name and address to whom correspondence concerning document should be mailed:</b></p> <p>Name: <u>Daryl K. Neff</u> <u>LERNER, DAVID, LITTENBERG,</u> <u>KRUMHOLZ &amp; MENTLIK, LLP</u></p> <p>Internal Address: <u>Atty. Dkt.: TESHEL 5.2-002</u></p> <p>Street Address: <u>600 South Avenue West</u></p> <p>City: <u>Westfield</u> State: <u>NJ</u> Zip: <u>07090</u> Phone Number: <u>(908) 518-6396</u> Fax Number: <u>(908) 654-0415</u> Email Address: <u>dneff@ldlkm.com</u></p>	<p><b>6. Total number of applications and patents involved:</b> <span style="border: 1px solid black; padding: 2px;">4</span></p> <p><b>7. Total fee (37 CFR 1.21(h) &amp; 3.41)</b> \$ <u>160.00</u></p> <p><input type="checkbox"/> Authorized to be charged by credit card  <input checked="" type="checkbox"/> Authorized to be charged to deposit account  <input type="checkbox"/> Enclosed  <input type="checkbox"/> None required (government interest not affecting title)</p> <p><b>8. Payment Information</b></p> <p>a. Credit Card Last 4 Numbers _____ Expiration Date _____</p> <p>b. Deposit Account Number <u>12-1095</u> Authorized User Name <u>Daryl K. Neff</u></p>
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<p><b>9. Signature:</b></p> <p style="text-align: center;"> _____ Signature</p> <p><u>Daryl K. Neff - 38,253</u> Name of Person Signing</p>	<p style="text-align: right;">March 30, 2011 Date</p> <p>Total number of pages including cover sheet, attachments, and documents: <span style="border: 1px solid black; padding: 2px;">5</span></p>
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CH \$160.00 121095 1207250

## PATENT ASSIGNMENT

In consideration of the sum of \$1.00 US, and for other such good and valuable consideration, the receipt of which is hereby acknowledged, Tessera, Inc., a corporation of the state of Delaware, having a place of business at 3025 Orchard Parkway, San Jose, California 95134, US, (hereinafter "ASSIGNOR"), hereby sells, transfers and assigns to Tessera Technologies Ireland Limited., a corporation of Ireland, having a place of business at Cliona, Building One, Parkmore East Business Park, Ballybrit, Galway, Ireland (hereinafter "ASSIGNEE"), all of ASSIGNOR'S right, title and interest in and to (i) the patent applications identified in Exhibit A attached hereto, and (ii) patents that may issue or reissue from any of the foregoing (together with all extensions, reexaminations and substitutions of any of the foregoing), (hereinafter, all such patents and patent applications, collectively, "ASSIGNED PATENTS"), to have and to hold the same, unto ASSIGNEE and/or its successors and assigns, including all damages for infringement of any of the ASSIGNED PATENTS and the sole right to sue therefore under such ASSIGNED PATENTS, for the full term or terms of all such ASSIGNED PATENTS, subject to all rights previously granted under the ASSIGNED PATENTS to third parties.

ASSIGNOR hereby declares that ASSIGNEE may take the steps for recordal of this assignment in the sole name of ASSIGNEE.

IN WITNESS WHEREOF, ASSIGNOR has caused this Patent Assignment to be duly signed on its behalf and ASSIGNEE has caused this Patent Assignment to be duly signed on its behalf.

This Assignment may be executed in any number of counterparts, each of which shall be deemed an original, but all of which together shall constitute one instrument.

**[Signatures follow on Page 2]**

SIGNED for and on behalf of ASSIGNOR:

Signature: [Signature] Date: March 25, 2011  
Name: Bernard J. Cassidy  
Title: Executive Vice President, General Counsel and Secretary

State of California )S.S.

County of Santa Clara )

On March 25, 2011, before me, Jennifer Kostic, Notary Public, personally appeared Bernard J. Cassidy, who proved to me on the basis of satisfactory evidence to be the person whose name is subscribed to the within instrument and acknowledged to me that he/she executed the same in his/her authorized capacity, and that by his/her signature on the instrument the person(s), or the entity upon behalf of which he/she acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.



Notary Signature [Signature] (Seal)

SIGNED for and on behalf of ASSIGNEE:

Signature: [Signature] Date: 3-25, 2011  
Name: Michael Anthofer  
Title: Director

State of California ) SS:

County of Santa Clara )

On March 25, 2011, before me, Jennifer Kostic, Notary Public, personally appeared Michael Anthofer, who proved to me on the basis of satisfactory evidence to be the person whose name is subscribed to the within instrument and acknowledged to me that he/she executed the same in his/her authorized capacity, and that by his/her signature on the instrument the person(s), or the entity upon behalf of which he/she acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.



Notary Signature [Signature] (Seal)  
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<b>EXHIBIT A</b>			
Patent applications assigned from Tessera, Inc. to Tessera Technologies Ireland Limited			
<b>Application Number</b>	<b>Country</b>	<b>Title</b>	<b>Reference Number</b>
12/072,508	United States	CHIPS HAVING REAR CONTACTS CONNECTED BY THROUGH VIAS TO FRONT CONTACTS	TESSERA 3.0-563
12/784,841	United States	CHIPS HAVING REAR CONTACTS CONNECTED BY THROUGH VIAS TO FRONT CONTACTS	TESSERA 3.0-563 DIV
200880014764.9	China	CHIPS HAVING REAR CONTACTS CONNECTED BY THROUGH VIAS TO FRONT CONTACTS	TESSERA 3.4-563 CHINA
08726232.5	European Patent Convention	CHIPS HAVING REAR CONTACTS CONNECTED BY THROUGH VIAS TO FRONT CONTACTS	TESSERA 3.4-563 EP
2009-552696	Japan	CHIPS HAVING REAR CONTACTS CONNECTED BY THROUGH VIAS TO FRONT CONTACTS	TESSERA 3.4-563 JAPAN
10-2009-7020378	Korea	CHIPS HAVING REAR CONTACTS CONNECTED BY THROUGH VIAS TO FRONT CONTACTS	TESSERA 3.4-563 KOREA
12/221,204	United States	SEMICONDUCTOR PACKAGING PROCESS USING THROUGH SILICON VIAS	TESSERA 3.0-582
200880106618.9	China	SEMICONDUCTOR PACKAGING PROCESS USING THROUGH SILICON VIAS	TESSERA 3.4-582 China
08795005.1	European Patent Convention	SEMICONDUCTOR PACKAGING PROCESS USING THROUGH SILICON VIAS	TESSERA 3.4-582 EP
627/KOLNP/2010	India	SEMICONDUCTOR PACKAGING PROCESS USING THROUGH SILICON VIAS	TESSERA 3.4-582 India
2010-519953	Japan	SEMICONDUCTOR PACKAGING PROCESS USING THROUGH SILICON VIAS	TESSERA 3.4-582 Japan

<u>Application Number</u>	<u>Country</u>	<u>Title</u>	<u>Reference Number</u>
10-2010-7004471	Korea	SEMICONDUCTOR PACKAGING PROCESS USING THROUGH SILICON VIAS	TESSERA 3.4-582 Korea
11/650,356	United States	MICROELECTRONIC ASSEMBLY WITH MULTI-LAYER SUPPORT STRUCTURE	TESSERA 3.0-528
1366964			